

HIGH-SPEED 3.3V 64K x18/x16 SYNCHRONOUS PIPELINED DUAL-PORT STATIC RAM

70V9289L *70V9389L

*SPECIFIED PART IS OBSOLETE NOT RECOMMENDED FOR NEW DESIGNS

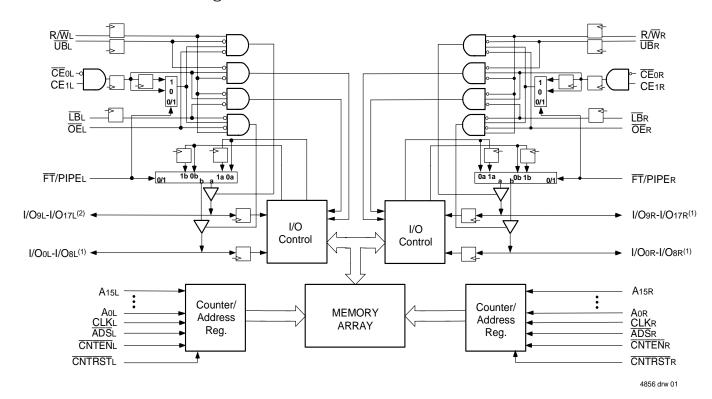
Features:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
 - Commercial: 7.5/9/12ns (max.)
 - Industrial: 9ns (max.)
- Low-power operation
 - IDT70V9389/289LActive: 500mW (typ.)
 - Standby: 1.5mW (typ.)
- Flow-Through or Pipelined output mode on either port via the FT/PIPE pins
- Counter enable and reset features
- Dual chip enables allow for depth expansion without additional logic
- LVTTL- compatible, single 3.3V (±0.3V) power supply

- Full synchronous operation on both ports
 - 4ns setup to clock and 0ns hold on all control, data, and address inputs
 - Data input, address, and control registers
 - Fast 7.5ns clock to data out in the Pipelined output mode
 - Self-timed write allows fast cycle time
 - 12ns cycle time, 83MHz operation in Pipelined output mode
- Separate upper-byte and lower-byte controls for multiplexed bus and bus matching compatibility
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Available in a 128-pin Thin Quad Flatpack (TQFP) and 100-pin Thin Quad Flatpack (TQFP)
- Green parts available, see ordering information

Note that information regarding recently obsoleted parts is included in this datasheet for customer convenience.

Functional Block Diagram



NOTES:

I/O₀x - I/O₇x for IDT70V9289.
 I/O₈x - I/O₁5x for IDT70V9289.

MARCH 2018

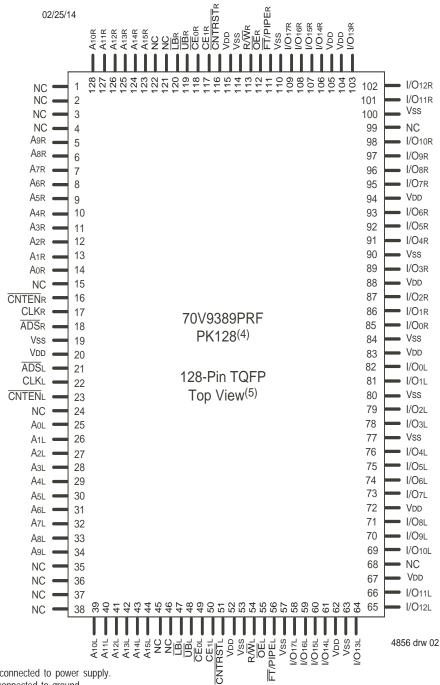


Description:

The IDT70V9389/289 is a high-speed 64K x 18 (64K x 16) bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times.

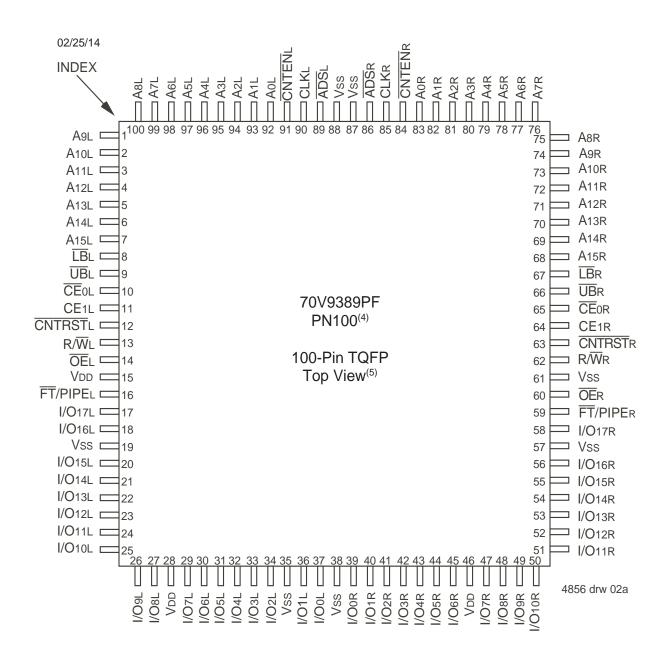
With an input data register, the IDT70V9389/289 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by $\overline{\text{CE}}$ 0 and CE1, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using CMOS high-performance technology, these devices typically operate on only 500mW of power.

Pin Configuration^(1,2,3)



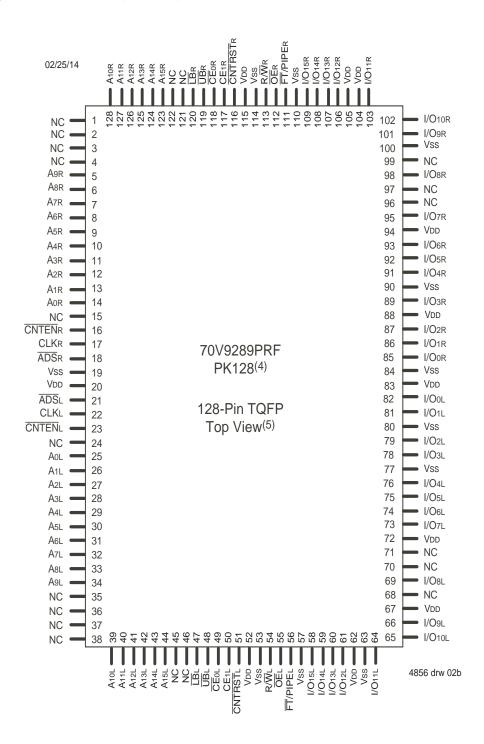
- 1. All VDD pins must be connected to power supply
- 2. All Vss pins must be connected to ground.
- 3. Package body is approximately 14mm x 20mm x 1.4mm.
- 4. This package code is used to reference the package diagram.
- This text does not indicate orientation of the actual part-marking.

Pin Configurations (1,2,3) (con't.)



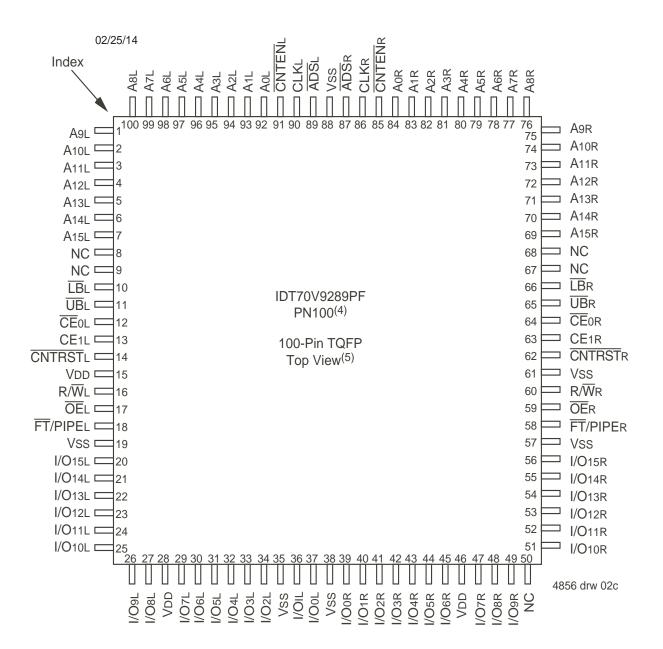
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Pin Names

Left Port	Right Port	Names		
CEOL, CE1L	CEOR, CE1R	Chip Enables ⁽³⁾		
R/WL	R/W̄R	Read/Write Enable		
ŌĒL	OE R	Output Enable		
A0L - A15L	A0R - A15R	Address		
I/O0L - I/O17L ⁽¹⁾	I/O0R - I/O17R ⁽¹⁾	Data Input/Output		
CLKL	CLKR	Clock		
UB L	UB R	Upper Byte Select ⁽²⁾		
LB L	∐B R	Lower Byte Select ⁽²⁾		
ADSL	ADS R	Address Strobe Enable		
CNTENL	CNTENR	Counter Enable		
CNTRSTL	CNTRSTR	Counter Reset		
FT/PIPEL	FT/PIPER	Flow-Through / Pipeline		
\	'DD	Power (3.3V)		
\	'ss	Ground (0V)		

4856 tbl 01

NOTES:

- 1. I/O₀x I/O₁₅x for IDT70V9289.
- 2. \overline{LB} and \overline{UB} are single buffered regardless of state of $\overline{FT}/PIPE$.
- 3. $\overline{\text{CE}}$ o and CE1 are single buffered when $\overline{\text{FT}}/\text{PIPE} = V_{\text{IL}}$, $\overline{\text{CE}}\text{o}$ and CE1 are double buffered when $\overline{\text{FT}}/\text{PIPE} = V_{\text{IH}}$, i.e. the signals take two cycles to deselect.

Truth Table I—Read/Write and Enable Control (1,2,3)

ŌĒ	CLK	ՇĒ ₀ ⁽⁵⁾	CE1 ⁽⁵⁾	ŪB ⁽⁴⁾	LB ⁽⁴⁾	R/W	Upper Byte I/O ₉₋₁₇ (6)	Lower Byte I/O ₀₋₈ ⁽⁷⁾	MODE
Х	1	Н	Х	Х	Х	Х	High-Z High-Z De		Deselected-Power Down
Х	1	Χ	L	Χ	Χ	Χ	High-Z	High-Z High-Z Deselected–Power Down	
Х	1	L	Н	Н	Н	Χ	High-Z	High-Z	Both Bytes Deselected
Х	1	L	Н	L	Н	L	Din	High-Z	Write to Upper Byte Only
Х	1	L	Н	Н	L	L	High-Z	Z DATAIN Write to Lower Byte Only	
Х	1	L	Н	L	L	L	DATAIN	DATAIN	Write to Both Bytes
L	1	L	Н	L	Н	Н	DATAout	High-Z	Read Upper Byte Only
L	1	L	Н	Н	L	Н	High-Z	DATAout	Read Lower Byte Only
L	1	L	Н	L	L	Н	DATAout	DATAout	Read Both Bytes
Н	Χ	L	Н	L	L	Х	High-Z	High-Z	Outputs Disabled

4856 tbl 02

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care. 2. ADS, CNTEN, CNTRST = X.
- 3. OE is an asynchronous input signal.
- 4. \overline{LB} and \overline{UB} are single buffered regardless of state of $\overline{FT}/PIPE$.
- 5. $\overline{\text{CE}}$ o and CE1 are single buffered when $\overline{\text{FT}}/\text{PIPE} = V_{\text{IL}}$. $\overline{\text{CE}}$ o and CE1 are double buffered when $\overline{\text{FT}}/\text{PIPE} = V_{\text{IH}}$, i.e. the signals take two cycles to deselect.
- 6. I/O₈ I/O₁₅ for IDT70V9289.
- 7. I/O₀ I/O₇ for IDT70V9289.

Truth Table II—Address Counter Control^(1,2)

External Address	Previous Internal Address	Internal Address Used	CLK	ĀDS	CNTEN	CNTRST	I/O ⁽³⁾	MODE		
Х	Х	0	1	Х	Х	L ⁽⁴⁾	Dvo(0)	Counter Reset to Address 0		
An	Х	An	1	L ⁽⁴⁾	Х	Н	Dvo(n)	External Address Loaded into Counter		
An	Ар	Ар	1	Н	Н	Н	Dvo(p)	External Address Blocked—Counter disabled (Ap reused)		
Х	Ар	Ap + 1	1	Н	L ⁽⁵⁾	Н	Di/o(p+1)	Counter Enabled—Internal Address generation		

4856 tbl 03

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care.
- 2. \overline{CE}_0 , \overline{LB} , \overline{UB} , and \overline{OE} = VIL; CE1 and R/ \overline{W} = VIH.
- 3. Outputs configured in Flow-Through Output mode; if outputs are in Pipelined mode the data out will be delayed by one cycle.
- 4. ADS and CNTRST are independent of all other signals including CEo, CE1, UB and LB.
- 5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CEo, CE1, UB and LB.

Recommended Operating Temperature and Supply Voltage⁽¹⁾

Grade	Ambient Temperature ⁽²⁾	GND	V DD
Commercial	0°C to +70°C	0V	3.3V <u>+</u> 0.3V
Industrial	-40°C to +85°C	0V	3.3V <u>+</u> 0.3V

NOTE: 4856 tbl 04

1. This is the parameter Ta. This is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Мах.	Unit
VDD	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
VIH	Input High Voltage	2.0	_	VDD+0.3V ⁽²⁾	V
VIL	Input Low Voltage	-0.3 ⁽¹⁾	_	0.8	V

4856 tbl 05

NOTES:

NOTES:

- 1. $VIL \ge -1.5V$ for pulse width less than 10 ns.
- 2. VTERM must not exceed VDD +0.3V.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
TBIAS ⁽³⁾	Temperature Under Bias	-55 to +125	°C
Тѕтс	Storage Temperature	-65 to +150	°C
NuT	Junction Temperature	+150	°C
Іоит	DC Output Current	50	mA

NOTES:

4856 tbl 06

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VTERM must not exceed VDD +0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to < 20mA for the period of VTERM > VDD + 0.3V.
- 3. Ambient Temperature Under DC Bias. No AC Conditions. Chip Deselected.

Capacitance⁽¹⁾

 $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter	Conditions ⁽²⁾	Max.	Unit
Cin	Input Capacitance	VIN = 3dV	9	pF
Соит ⁽³⁾	Output Capacitance	Vout = 3dV	10	pF

4856 tb

- These parameters are determined by device characterization, but are not production tested.
- 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
- 3. Cout also references C_{1/0}.

4856 tbl 08



70V9389/289L High-Speed 3.3V 64K x18/x16 Dual-Port Synchronous Pipelined Static RAM

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (VDD = 3.3V ± 0.3V)

				70V9389/289L		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit	
Iu	Input Leakage Current ⁽¹⁾	VDD = 3.6V, VIN = 0V to VDD	_	5	μΑ	
ILO	Output Leakage Current	\overline{CE} = ViH or CE1 = ViL, Vout = 0V to VDD	_	5	μΑ	
Vol	Output Low Voltage	IoL = +4mA	_	0.4	V	
Vон	Output High Voltage	IOH = -4mA	2.4	_	٧	

NOTE:

1. At V_{DD} ≤ 2.0V input leakages are undefined.

DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range⁽³⁾ (VDD = 3.3V ± 0.3V)

						9/289L7 I Only	70V938 Com'l	9/289L9 & Ind		9/289L12 I Only	
Symbol	Parameter	Test Condition	Versio	n	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Unit
IDD	Dynamic Operating Current (Both		COM'L	L	200	250	175	230	150	200	mA
	Ports Active)	Outputs Disabled, f = fMAX ⁽¹⁾	IND	L	_	_	180	240		_	
ISB1	Standby Current (Both Ports - TTL	CEL = CER = VIH	COM'L	L	50	75	40	65	30	50	mA
	Level Inputs)	$f = fMAX^{(1)}$	IND	L	_	_	50	70		_	
ISB2	Standby Current (One	CE"A" = VIL and CE"B" = VIH(5) Active Port Outputs Disabled, f=fMAX(1)	COM'L	L	130	165	110	145	95	130	mA
	Port - TTL Level Inputs)		IND	L	_	_	110	155	_		
ISB3	Full Standby Current (Both	Both Ports $\overline{CE}L$ and $\overline{CE}R \ge VDD - 0.2V$,	COM'L	L	0.4	2	0.4	2	0.4	2	mA
	Ports - CMOS Level Inputs)	$VIN \ge VDD - 0.2V$, $VIN \ge VDD - 0.2V$ or $VIN \le 0.2V$, $f = 0^{(2)}$	IND	L	_	_	0.4	2	_		
ISB4	Full Standby	<u>CE</u> "A" ≤ 0.2V and	COM'L	L	130	160	100	140	90	125	mA
	Current (One Port - CMOS Level Inputs)		IND	L	_	_	100	155	_	_	

NOTES

1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.

- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. $\underline{VDD} = 3.3V$, $TA = \underline{25}^{\circ}C$ for Typ, and are not production tested. \underline{IDD} $\underline{DC}(f=0) = 90\text{mA}$ (Typ).
- 5. $\overline{CE}x = VIL \text{ means } \overline{CE}_0x = VIL \text{ and } CE_1x = VIH$
 - $\overline{CE}x = V_{IH} \text{ means } \overline{CE}_{0X} = V_{IH} \text{ or } CE_{1X} = V_{IL}$
 - $\overline{\text{CE}}\text{x} \leq 0.2 \text{V}$ means $\overline{\text{CE}}\text{ox} \leq 0.2 \text{V}$ and $\text{CE}\text{1x} \geq \text{V}\text{DD}$ 0.2 V
 - $\overline{\text{CE}}\text{X} \geq \text{V}_{\text{DD}}$ 0.2V means $\overline{\text{CE}}_{\text{0}}\text{X} \geq \text{V}_{\text{CC}}$ 0.2V or $\text{CE}_{\text{1}}\text{X} \leq 0.2\text{V}$
 - "X" represents "L" for left port or "R" for right port.



AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1, 2, and 3

4856 tbl 10

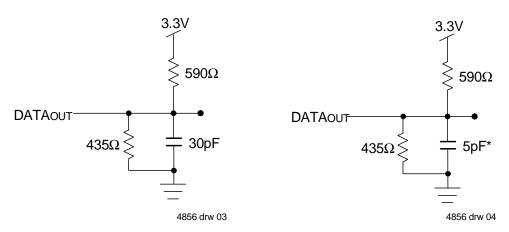


Figure 1. AC Output Test load.

Figure 2. Output Test Load (For tckLz, tckHz, toLz, and toHz). *Including scope and jig.

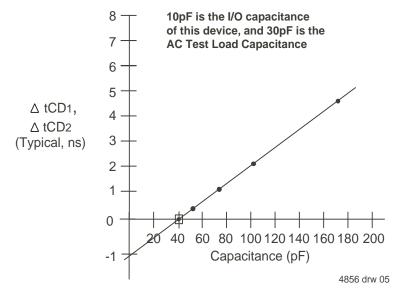


Figure 3. Typical Output Derating (Lumped Capacitive Load).



AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing) $^{(3)}$ (VDD = 3.3V ± 0.3V)

•	and write cycle riming) (**)	70V938	89/289L7 'I Only	70V9389/289L9 Com'l & Ind		70V9389/289L12 Com'l Only		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	22	_	25	_	30	_	ns
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	12		15		20	_	ns
tcH1	Clock High Time (Flow-Through) ⁽²⁾	7.5		12		12	_	ns
tcl1	Clock Low Time (Flow-Through) ⁽²⁾	7.5	-	12		12	_	ns
tcH2	Clock High Time (Pipelined) ⁽²⁾	5		6		8	_	ns
tCL2	Clock Low Time (Pipelined) ⁽²⁾	5	-	6		8	_	ns
tr	Clock Rise Time	_	3	_	3	_	3	ns
tF	Clock Fall Time	_	3	_	3	_	3	ns
tsa	Address Setup Time	4		4		4	_	ns
tна	Address Hold Time	0		1		1	_	ns
tsc	Chip Enable Setup Time	4		4		4	_	ns
thc	Chip Enable Hold Time	0		1		1	_	ns
tsB	Byte Enable Setup Time	4		4		4	_	ns
tнв	Byte Enable Hold Time	0		1		1	_	ns
tsw	R/W Setup Time	4		4		4	_	ns
thw	R/W Hold Time	0		1		1	_	ns
tsd	Input Data Setup Time	4		4		4	_	ns
thd	Input Data Hold Time	0		1		1	_	ns
tsad	ADS Setup Time	4		4		4	_	ns
thad	ADS Hold Time	0	_	1	_	1	_	ns
tscn	CNTEN Setup Time	4		4		4	_	ns
thcn	CNTEN Hold Time	0		1		1	_	ns
tsrst	CNTRST Setup Time	4		4		4	_	ns
thrst	CNTRST Hold Time	0		1		1	_	ns
toe	Output Enable to Data Valid	_	7.5	_	9		12	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2		2		2	_	ns
tонz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	1	7	ns
tcd1	Clock to Data Valid (Flow-Through) ⁽²⁾		18	_	20	_	25	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾	_	7.5	_	9	_	12	ns
toc	Data Output Hold After Clock High	2		2		2	_	ns
tckhz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	2	9	ns
tcklz	Clock High to Output Low-Z ⁽¹⁾	2		2		2	_	ns
Port-to-Port I	Delay	L						
tcwdd	Write Port Clock High to Read Data Delay	_	28	_	35	_	40	ns
tccs	Clock-to-Clock Setup Time	_	10	_	15	_	15	ns

NOTES: 4856 tbl 11:

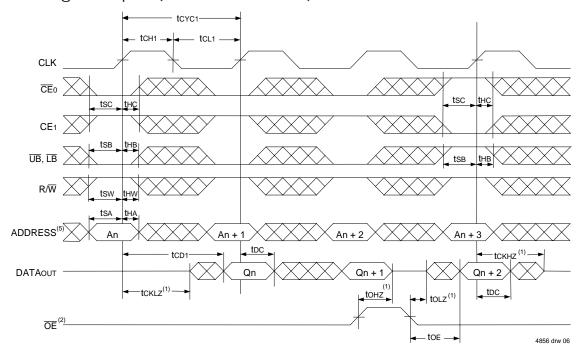
^{1.} Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

^{2.} The Pipelined output parameters (tcyc2, tcb2) apply to either or both the Left and Right ports when FT/PIPE = ViH. Flow-through parameters (tcyc1, tcb1) apply when FT/PIPE = ViL for that port.

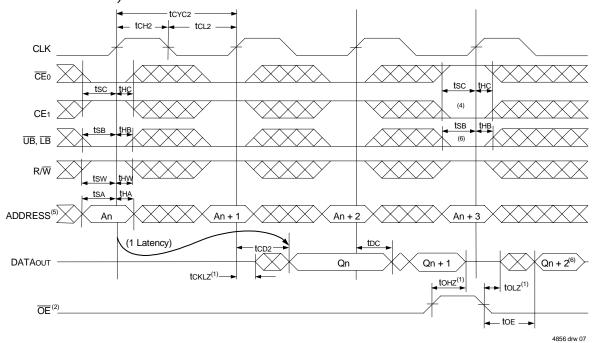
^{3.} All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE), FT/PIPER, and FT/PIPEL.



Timing Waveform of Read Cycle for Flow-Through Output $(\mathbf{FT}/PIPE"x" = Vil)^{(3,7)}$



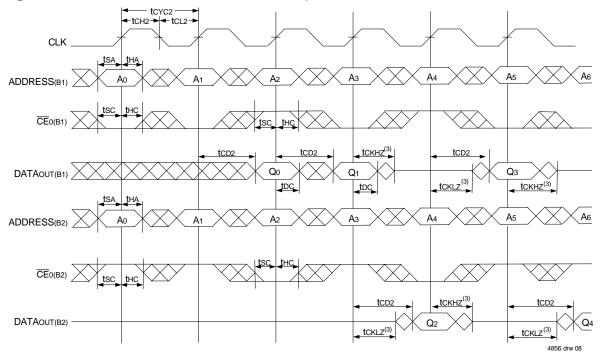
Timing Waveform of Read Cycle for Pipelined Operation $(FT/PIPE"x" = VIH)^{(3,7)}$



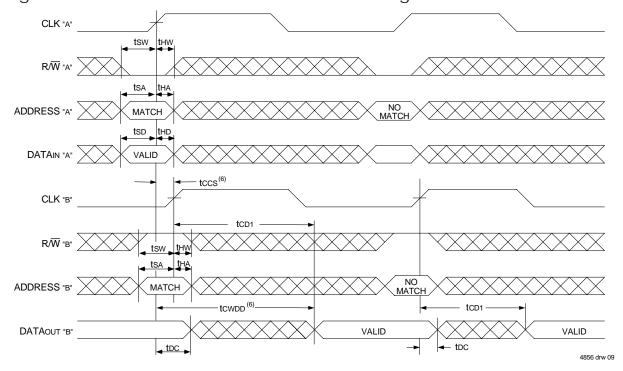
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. $\overline{\text{OE}}$ is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. $\overline{ADS} = VIL \text{ and } \overline{CNTRST} = VIH.$
- 4. The output is disabled (High-Impedance state) by $\overline{\text{CE}}_0 = \text{V}_{\text{IH}}$, $\overline{\text{CE}}_1 = \text{V}_{\text{IL}}$, $\overline{\text{UB}} = \text{V}_{\text{IH}}$, or $\overline{\text{LB}} = \text{V}_{\text{IH}}$ following the next rising edge of the clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 6. If UB or LB was HIGH, then the Upper Byte and/or Lower Byte of DATAou⊤ for Qn + 2 would be disabled (High-Impedance state).
- 7. "X' here denotes Left or Right port. The diagram is with respect to that port.



Timing Waveform of a Bank Select Pipelined Read (1,2)



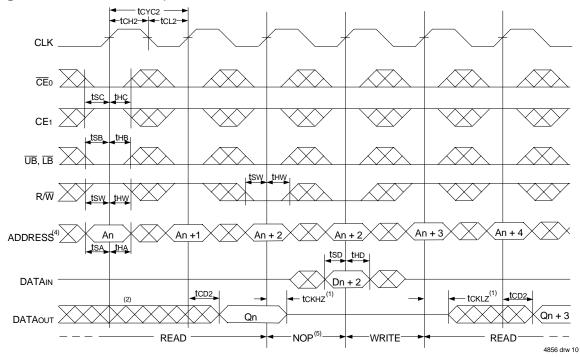
Timing Waveform with Port-to-Port Flow-Through Read (4,5,7)



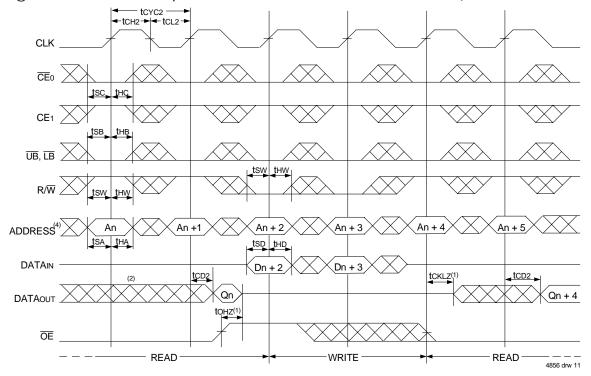
- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V9389 or IDT70V9289 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{UB} , \overline{LB} , \overline{OE} , and \overline{ADS} = VIL; CE1(B1), CE1(B2), R/ \overline{W} and \overline{CNTRST} = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. \overline{CE}_0 , \overline{UB} , \overline{LB} , and \overline{ADS} = VIL; CE1 and \overline{CNTRST} = VIH.
- 5. $\overline{OE} = VIL$ for the Right Port, which is being read from. $\overline{OE} = VIH$ for the Left Port, which is being written to.
- If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwbb.
 If tccs > maximum specified, then data from right port READ is not valid until tccs + tcb1. tcwbb does not apply in this case.
- 7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite from Port "A".



Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** = VIL)(3)



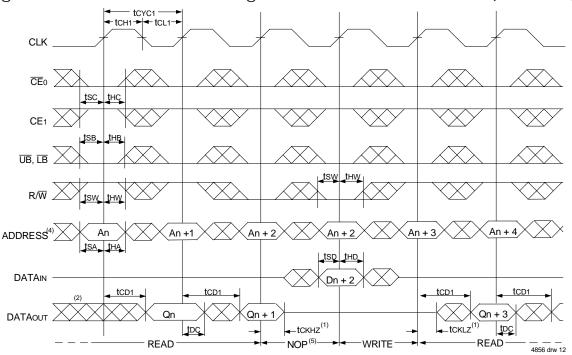
Timing Waveform of Pipelined Read-to-Write-to-Read (**©E** Controlled)(3)



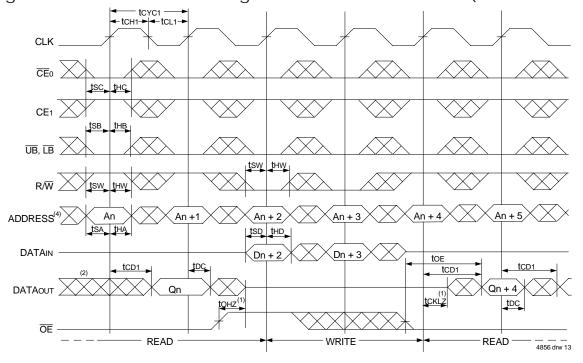
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- Output state (High, Low, or High-impedance) is determined by the previous cycle control signals. $\overline{\text{CE}}_0$, $\overline{\text{UB}}$, $\overline{\text{LB}}$, and $\overline{\text{ADS}}$ = VIL; CE1 and $\overline{\text{CNTRST}}$ = VIH. "NOP" is "No Operation".
- Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.



Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** = VIL)⁽³⁾



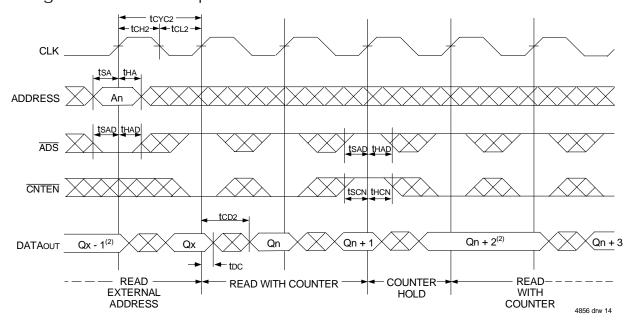
Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)⁽³⁾



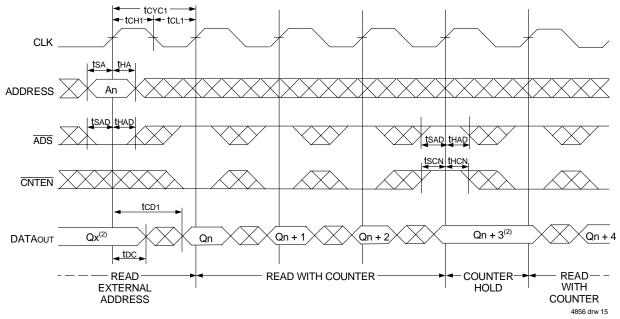
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. \overline{CE}_0 , \overline{UB} , \overline{LB} , and \overline{ADS} = VIL; CE1 and \overline{CNTRST} = VIH. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.



Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾

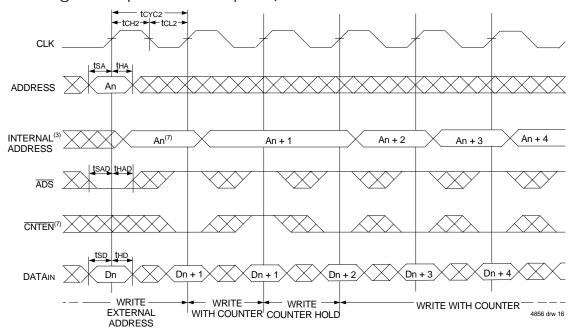


Timing Waveform of Flow-Through Read with Address Counter Advance⁽¹⁾

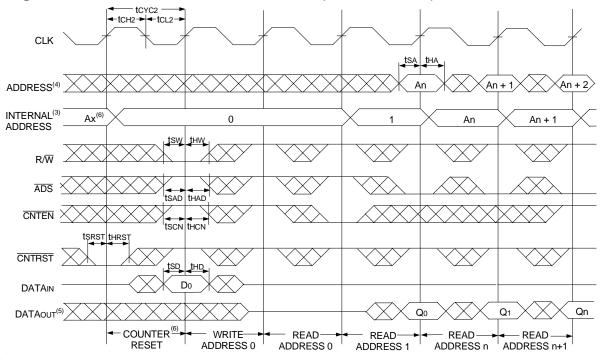


- 1. \overline{CE}_0 , \overline{OE} , \overline{UB} , and \overline{LB} = VIL; CE1, R/ \overline{W} , and \overline{CNTRST} = VIH.
- 2. If there is no address change via $\overline{ADS} = V_{IL}$ (loading a new address) or $\overline{CNTEN} = V_{IL}$ (advancing the address), i.e. $\overline{ADS} = V_{IH}$ and $\overline{CNTEN} = V_{IH}$, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾



Timing Waveform of Counter Reset (Pipelined Outputs)(2)



NOTES:

1. $\overline{\text{CE}}_0$, $\overline{\text{UB}}$, $\overline{\text{LB}}$, and $R/\overline{W} = \text{ViL}$; CE1 and $\overline{\text{CNTRST}} = \text{ViH}$.

- 2. \overline{CE}_0 , \overline{UB} , \overline{LB} = VIL; CE1 = VIH.
- 3. The "Internal Address" is equal to the "External Address" when $\overline{ADS} = VIL$ and equals the counter output when $\overline{ADS} = VIH$.
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. ADDRo will be accessed. Extra cycles are shown here simply for clarification.
- 7. CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1' Address is written to during this cycle.



Functional Description

The IDT70V9389/289 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

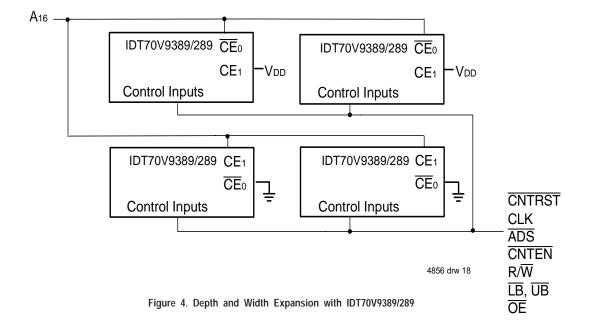
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to staff the operation of the address counters for fast interleaved memory applications.

 $\overline{\text{CE}}_0$ = VIH or CE1 = VIL for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9389/289's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with $\overline{\text{CE}}_0$ = VIL and CE1 = VIH to re-activate the outputs.

Depth and Width Expansion

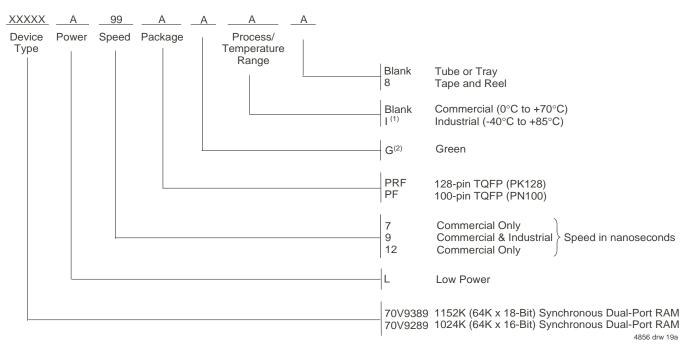
The IDT70V9389/289 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT70V9389/289 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 36/32-bit orwider applications.





Ordering Information



NOTES:

- 1. Industrial temperature range is available. For specific speeds, packages and powers contact your sales office.
- Green parts available. For specific speeds, packages and powers contact your local sales office. LEAD FINISH (SnPb) parts are Obsolete. Product Discontinuation Notice - PDN# SP-17-02 Note that information regarding recently obsoleted parts is included in this datasheet for customer convenience.

IDT Clock Solution for IDT70V9389/289 Dual-Port

	Dual-Port I/O	Specitications		Dual-Port Clock S	IDT	IDT			
IDT Dual-Port Part Number	Voltage I/O		Input Capacitance	Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	PLL Clock Devices	Non-PLL Clock	
70V9389/289	3.3	LVTTL	9pF	40%	100	150ps	IDT2305 IDT2308 IDT2309	49FCT3805 49FCT3805D/E 74FCT3807 74FCT3807D/E	

4856 tbl12



Datasheet Document History

09/30/99: Initial Public Release 11/12/99: Replaced IDT logo

06/23/00: Page 3 Changed information in Truth Table II

Page 4 Increased storage temperature parameters

Clarified TA parameter

Page 5 DC Electrical parameters—changed wording from "open" to "disabled"

Changed ±200mV to 0mV in notes

04/09/03: Consolidated multiple devices into one datasheet

Changed naming conventions from Vcc to Vdd and from GND to Vss

Page 3 & 5 Added PN-100 TQFP pin configuration

Page 1 & 18 Added PN-100 TQFP availability and ordering information

Page 2 - 5 Added date revision to pin configurations

Page 7 Added junction temperature to Absolute Maximum Ratings Table

Added Ambient Temperature footnote

Page 8, 10 & 18 Added 6ns speed grade

Page 8 Added updated DC power numbers to the DC Electrical Characteristics Table

Page 10 Added 6ns speed AC timing numbers and changed to Et o be equal to top2 in the AC Electrical Characteristics

Table

Page 18 Added IDT Clock Solution Table
Page 1& 19 Removed "Preliminary" status

Added groop availability to feature

01/10/06: Page 1 Added green availability to features

Page 18 Added green indicator to ordering information

06/03/08: Page 8, 10 & 18 Designated 6ns speed grade available in PK-128 package only

01/19/09: Page 18 Removed "IDT" from orderable part number

07/26/10: Page 10 In order to correct the header notes of the AC Elect Chars Table and align them with the Industrial temp range

values located in the table, the commercial TA header note has been removed

Pages 11-14 In order to correct the footnotes of timing diagrams, CNTEN has been removed to reconcile the footnotes with

the CNTEN logic definition found in Truth Table II - Address Counter Control

03/17/14: Page 1,8,10 & 18 Removed 6ns commercial grade speed from Features, DC & AC Electrical Chars tables

Page 2 & 4 The label PK-128-1 changed to PK128 in the Pin configurations and in the Ordering Information

to accurately match the standard package code

Page 3 & 5 The label PN100-1 changed to PN100 in the Pin configurations and in the Ordering Information

to accurately match the standard package code

Page 9 Corrected a typo

Page 18 Added Tape & Reel indicator to Ordering Information

03/01/18: Product Discontinuation Notice - PDN# SP-17-02

Last time buy expires June 15, 2018

04/24/19: 70V9389 is obsolete

70V9289 is active

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